

What is claimed is:

1. A method for connecting an integrated circuit to a substrate, comprising:

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providing a package for the integrated circuit, which has a connection side, on which there are provided a plurality of connection regions for connection to the substrate;

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providing a corresponding plurality of connection regions on the substrate;

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providing elevated contact regions on the connection regions of the package and/or the connection regions of the substrate, the elevated contact regions comprising a first group of contact regions and a second group of contact regions; and

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creating a connection of the package to the substrate via the elevated contact regions, the elevated contact regions configured such that the first group of contact regions form a rigid connection and the second group of contact regions form an elastic connection between the

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2. The method according to claim 1, wherein the first group of contact regions is arranged in a near region surrounding a point of the connection side, and the

30 second group of contact regions is arranged outside in a far region surrounding the near region.

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3. The method according to claim 2, wherein the point lies approximately in a center of an extent in a

35 predetermined direction of the package.

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4. The method according to claim 1, wherein the contact regions of the first group comprise solder elements and the contact regions of the second group comprise plastic elements.

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5. The method according to claim 4, wherein the plastic elements comprise electrically conductive polymer and/or adhesive and/or silicone.

10 6. The method according to claim 5, wherein the plastic elements are provided with a solderable metal coating at their side to be connected.

15 7. The method according to claim 4, wherein the plastic elements comprise electrically nonconductive polymer and/or adhesive and/or silicone and are provided with a metallic interconnect at their side to be connected, the interconnect being electrically connected to the integrated circuit.

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8. The method according to claim 1, wherein the package has an interposer on the front side of the integrated circuit, the connection regions of the package are provided on a side of the interposer which is remote from the integrated circuit.

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9. The method according to claim 1, wherein the package has an insulating layer on the front side of the integrated circuit, the connection regions of the package are provided on a side of the insulating layer which is remote from the integrated circuit.

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10. The method according to claim 1, wherein the package is provided at least on the rear side of the integrated circuit as an encapsulation.

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11. A circuit arrangement having a connection of an integrated circuit to a substrate, comprising:

5 a package of the integrated circuit, which has a connection side, on which there are provided a plurality of connection regions for connection to the substrate;

a corresponding plurality of connection regions on the substrate; and

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elevated contact regions, which connect the connection regions of the package to the connection regions of the substrate, the elevated contact regions comprising a first group of contact regions and a second group of  
15 contact regions, which are configured such that the first group of contact regions form a rigid connection and the second group of contact regions form an elastic connection between the package and the substrate.

20 12. The method according to claim 11, wherein the first group of contact regions is arranged in a near region surrounding a point of the connection side, and the second group of contact regions is arranged outside in a far region surrounding the near region.

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13. The method according to claim 12, wherein the point lies approximately in a center of an extent in a predetermined direction of the package.

30 14. The method according to claim 11, wherein the contact regions of the first group comprise solder elements and the contact regions of the second group comprise plastic elements.

35 15. The method according to claim 14, wherein the plastic elements comprise electrically conductive polymer and/or adhesive and/or silicone.

16. The method according to claim 15, wherein the plastic elements are provided with a solderable metal coating at their side to be connected.

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17. The method according to claim 14, wherein the plastic elements comprise electrically nonconductive polymer and/or adhesive and/or silicone and are provided with a metallic interconnect at their side to be  
10 connected, the interconnect being electrically connected to the integrated circuit.

18. The method according to claim 11, wherein the package has an interposer on the front side of the  
15 integrated circuit, the connection regions of the package being provided on a side of the interposer which is remote from the integrated circuit.

19. The method according to claim 11, wherein the  
20 package has an insulating layer on the front side of the integrated circuit, the connection regions of the package provided on a side of the insulating layer which is remote from the integrated circuit.

25 20. The method according to claim 1, wherein the package is provided at least on the rear side of the integrated circuit as an encapsulation.